

providing a dry-etching apparatus having:

a) a process chamber having a gas inlet, the gas inlet allowing a reactive gas into the process chamber;

b) a first electrode arranged at a predetermined location in the process chamber;

c) a second electrode in the chamber spaced apart from and opposite to the first electrode, having an insulating tape thereon, a plurality of lift pins received in a plurality of holes, the insulating tape being arranged between the plurality of the lift pins, wherein said insulating tape reduces an electrostatic attraction between the second electrode and the array substrate; and

d) a power source for applying voltages to the first and second electrodes;

arranging the array substrate on the second electrode;

dry-etching the array substrate; and

separating the array substrate from the second electrode using the lift pins.

15. (Amended) A method for preventing an array substrate from being

damaged due to an electrostatic force after a dry-etching process, comprising:

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providing a dry-etching apparatus having a first and a second electrodes in a process chamber, the second electrode having a plurality of holes and lift pins, and an insulating tape thereon, wherein said insulating tape reduces an electrostatic attraction between the second electrode and the array substrate;
arranging the array substrate on the second electrode;
dry-etching the array substrate; and
separating the array substrate from the second electrode using the lift pins.

17. (Amended) A method of processing a substrate for a liquid crystal display (LCD) device, the method comprising:
providing an electrode plate;
positioning a substrate at a predetermined distance from the electrode plate to obtain an intermediate structure, wherein said positioning reduces electrostatic attraction between said substrate and said electrode plate;
processing the intermediate structure; and
removing the substrate from the electrode plate.

20. (Amended) A method of processing a substrate for a liquid crystal display (LCD) device, the method comprising:
providing an electrode;

providing an intermediate material on the electrode;

providing a substrate on the intermediate material of the electrode to
obtain an intermediate structure;

processing the intermediate structure; and

removing the substrate from the electrode utilizing a plurality of pins
formed on the electrode to push the substrate away from the electrode, wherein
the intermediate material reduces electrostatic attraction between the substrate
and the electrode.
